



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2020-02-12
<b>Contact Name *</b>	Refer to Supplier comment section	<b>Contact Title</b>	Refer to Supplier comment section
<b>Contact Phone *</b>	Refer to Supplier comment section	<b>Contact Email *</b>	Refer to Supplier comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS Material Declaration Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	22AA*MV97ABA	B	MA1A	2020-02-12
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.0	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy	0	



Package Designator	Size	Nbr of instances	Shape	
LGA	2 x 2	12	flat	
Comment	A069 LGA2X2X0.7 12 LEADS; MDF is valid for IIS2MDCTR and LIS2MDL and LIS2MDLTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	TRUE
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.089	substrate	14833

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Morpholine derivative	1000	0.013	Substrate	2167
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material
Morpholine derivative	1000	0.013	Substrate	8626

Material Composition Declaration						Mfr Item Name	22AA*MV97ABA	6.0000	5900003.0	1000002.0						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	M-011 Other inorganic materials	0.556	mg	supplier	die	Silicon(Si)	7440-21-3		0.502	mg	902878	83667				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.010	mg	17986	1667				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.005	mg	8993	833				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.014	mg	25180	2333				
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.001	mg	1799	167				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.002	mg	3597	333				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	1799	167				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-6		0.005	mg	8993	833				
				supplier	passivation	Silicon Oxide	7631-86-9		0.016	mg	28777	2667				
				supplier	laminate	Fiber glass	65997-17-3		0.208	mg	138023	34667				
				supplier	laminate	Bisphenol F type epoxy resin	9003-36-5		0.192	mg	127405	32000				
				Substrate	M-015 Other organic materials	1.507	mg	supplier	laminate	Bismaleimide (B)	105391-33-1		0.070	mg	46450	11667
supplier	laminate	Triazine (T)	25722-66-1						0.070	mg	46450	11667				
supplier	laminate	Aluminium hydroxide	21645-51-2						0.005	mg	3318	833				
supplier	laminate	Zinc hydroxide	20427-58-1						0.001	mg	664	167				
supplier	laminate	Calcium sulfate	7778-18-9						0.002	mg	1327	333				
supplier	SVHC	laminate	BPA					80-05-7		0.001	mg	664	167			
supplier	laminate	Barium sulfate	7727-43-7						0.084	mg	55740	14000				
supplier	laminate	polymerized Biphenyl resin	85954-11-6						0.031	mg	20571	5167				
supplier	laminate	Talc containing no asbestosiform fibers	14807-96-6						0.021	mg	13935	3500				
supplier	laminate	Methoxymethylethoxy propanol	34590-94-8						0.018	mg	11944	3000				
supplier	laminate	Amorphous silica	7631-86-9						0.016	mg	10617	2667				
supplier	SVHC	laminate	Morpholine derivative					119313-12-1		0.013	mg	8626	2167			
supplier	laminate	Naphta	64742-94-5						0.003	mg	1991	500				
supplier	metallisation	Copper(Cu)	7440-50-8						0.695	mg	461181	115833				
supplier	metallisation	Nickel(Ni)	7440-02-0						0.075	mg	49768	12500				
supplier	metallisation	Gold(Au)	7440-57-5						0.002	mg	1327	333				
Die attach	M-015 Other organic materials	0.037	mg					supplier	tape	Epoxy resin	25068-38-6		0.023	mg	621622	3833
								supplier	tape	Polypropylene	9003-07-0		0.001	mg	27027	167
				supplier	tape	epoxy resin	29690-82-2		0.004	mg	108108	667				
				supplier	tape	Propenoate polymer	538311-13-6		0.007	mg	189189	1167				
				supplier	tape	Bisphenol A diglycidyl ether	1675-54-3		0.002	mg	54054	333				
				supplier	wire	Gold(Au)	7440-57-5		0.097	mg	989796	16167				
Bonding wire	M-008 Precious metals	0.098	mg	supplier	wire	Palladium(Pd)	7440-05-3		0.001	mg	10204	167				
				supplier	wire	Palladium(Pd)	7440-05-3		0.001	mg	10204	167				
encapsulation	M-015 Other organic materials	3.802	mg	supplier	mold compound	Silica vitreous	60676-86-0		3.441	mg	905050	573500				
				supplier	mold compound	Epoxyde bisphenol A resin	25068-38-6		0.095	mg	24987	15833				
				supplier	mold compound	Epoxy resin	proprietary		0.152	mg	39979	25333				
				supplier	mold compound	Phenol Resin	proprietary		0.095	mg	24987	15833				
				supplier	mold compound	Carbon black	1333-86-4		0.019	mg	4997	3167				